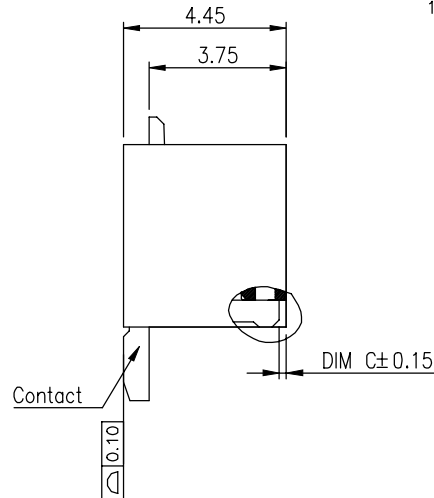
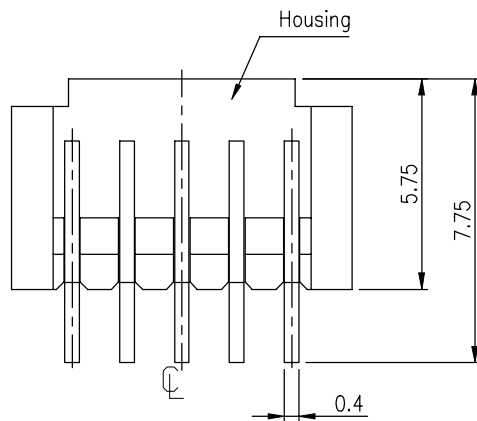


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



NOTES:

1. MATERIAL:

- 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0.
- 1.2 CONTACT: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

- 50~100u" NICKEL UNDERPLATING OVERALL.
- 1:CONTACT AREA 1~3u" GOLD FLASH.
- L:CONTACT AREA 100~200u" PURE TIN PLATING,
- N:CONTACT AREA 100~200u" MATT TIN PLATING.
- C:CONTACT AREA 15u" GOLD PLATING
- T:CONTACT AREA 10u" GOLD PLATING

2.2 SOLDER:

- 50~100u" NICKEL UNDERPLATING OVERALL.
- 1:SOLDER TAILS 1~3u" GOLD FLASH.
- L:SOLDER TAILS:100~200u" PURE TIN PLATING,
- N:SOLDER TAILS:100~200u" MATT TIN PLATING,
- C:SOLDER TAILS 0.5u"(MIN)GOLD FLASH PLATING

3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-50289-xxxxx-xxx

5. PART NUMBER

P/N LEGEND
50290-XXX X X-XXX

NO OF CKT
PACKING
0:TAPE & REEL
1:TUBE

XXX	LOG	MATERIAL & COLOR	Halogen Free	Packing	DIM C
001	Y	LCP&BLACK	HF	50290-XXXXXX-TRP	0
002	Y	LCP&BLACK	HF	50290-XXXXXX-L-XX-TR	0
003	N	LCP&WHITE	HF	50290-XXXXXX-TRP	0
004	Y	LCP&BLACK	HF	50290-XXXXXX-TRP	0.2
P01	Y	LCP&BLACK	HF	50290-XXXXXX-XX-TRP	0
P02	Y	NYLON&BLACK	HF	50290-XXXXXX-XX-TRP	0

PLATING
L:LEAD FREE (PURE TIN)
N:MATT TIN
1:G/F OVERALL
C:15u"Gold ON CONTACT
T:10u"Gold ON CONTACT

CKT	Dim A	Dim B
2	1.5	4.8
3	3.0	6.3
4	4.5	7.8
5	6.0	9.3
6	7.5	10.8
7	9.0	12.3
8	10.5	13.8
9	12.0	15.3
10	13.5	16.8
11	15.0	18.3
12	16.5	19.8
13	18.0	21.3
14	19.5	22.8
15	21.0	24.3
16	22.5	25.8
17	24.0	27.3
18	25.5	28.8
19	27.0	30.3
20	28.5	31.8

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Ding,shuqin DATE 22/05/09		TITLE 1.5mm WTB Header SMT R/A Type
	CHECKED BY Lu, jing quan DATE 22/05/09		
UNITS mm SCALE 1:1	SHEET NO. 1 OF 1	SIZE A4 REV M	RFG NO. N/A DWG NO. 50290-XXXXX-XXX